Product Specification		DOC.NO	1008CG-series
Product Description	SMD Wire Wound Ceramic Chip Inductor	Page	1
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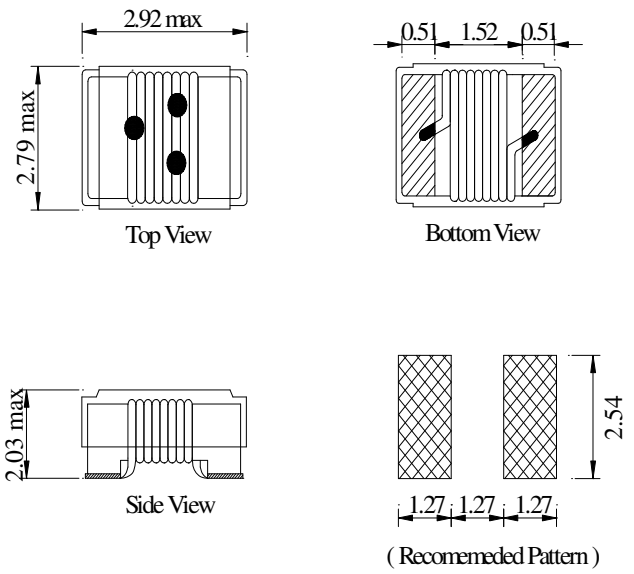
Configuration & Dimension:



Feature:

1、Small and lightweight surface mounting type.
2、Coil body made of ceramic material in chip from High Q at high frequency.
High self-resonance frequency.
Inductance Range:10~4700nH.
3、Applicable to 100MHz~2GMHz.

Application:

1、Bluetooth module.
2、Mobile communication units.
3、Portable telephone.
4、Wireless devices.

Construction & Material:

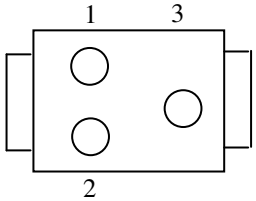
1、Core : Ceramic core
2、Wire : F Class Enameled copper wire
3、Terminal : Ag -Pd or W / Ni / Sn
4、Encapsulate : UV epoxy ；Color：Transparent
5、Products comply with RoHS' requirements

Product Identification:

1008 C ___ ___ ___
1 2 3 4 5

1、Dimension
2、Type: C : Standard products ., D~Z : Special products
3、Terminal : G : Mo / Mn or W with Gold plated.
S : Pd /Ag with Tin plated.
4、Inductance:
5、Tolerance: (G2%，J5%，K10%，M20%)

Color Code Reading Sequence:



Black=0 Green=5
Brown=1 Blue=6
Red=2 Violet=7
Orange=3 Gray=8
Yellow=4 White=9

Ex:10N(10nH) Color Code:
1:Brown 2:Black 3:Black

Specification / Electrical		DOC.NO	1008CG-type
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PART NUMBER	INDUCTANCE (n H)	Q MIN	SRF (MHz) MIN	RDC (Ω) MAX	IDC (mA) MAX	TOLERANCE	COLOR CODE		
							Point 1	Point 2	Point 3
1008C 10N	10@50MHz	50@500MHz	4100	0.08	1000	M、K	Brown	Black	Black
1008C 12N	12@50MHz	50@500MHz	3300	0.09	1000	M、K	Brown	Red	Black
1008C 15N	15@50MHz	50@500MHz	2500	0.10	1000	M、K	Brown	Green	Black
1008C 18N	18@50MHz	50@350MHz	2500	0.11	1000	M、K、J、G	Brown	Gray	Black
1008C 22N	22@50MHz	55@350MHz	2400	0.12	1000	M、K、J、G	Red	Red	Black
1008C 24N	24@50MHz	50@350MHz	1500	0.13	1000	M、K、J、G	Red	Yellow	Black
1008C 27N	27@50MHz	55@350MHz	1600	0.13	1000	M、K、J、G	Red	Violet	Black
1008C 33N	33@50MHz	60@350MHz	1600	0.14	1000	M、K、J、G	Orange	Orange	Black
1008C 39N	39@50MHz	60@350MHz	1500	0.15	1000	M、K、J、G	Orange	White	Black
1008C 47N	47@50MHz	65@350MHz	1500	0.16	1000	M、K、J、G	Yellow	Violet	Black
1008C 56N	56@50MHZ	65@350MHz	1300	0.18	1000	K、J、G	Green	Blue	Black
1008C 68N	68@50MHz	65@350MHz	1300	0.20	1000	K、J、G	Blue	Gray	Black
1008C 82N	82@50MHz	60@350MHz	1000	0.22	1000	K、J、G	Gray	Red	Black
1008C R10	100@25MHz	60@350MHz	1000	0.56	650	K、J、G	Brown	Black	Brown
1008C R12	120@25MHz	60@350MHz	950	0.63	650	K、J、G	Brown	Red	Brown
1008C R15	150@25MHz	45@100MHz	850	0.70	580	K、J、G	Brown	Green	Brown
1008C R18	180@25MHz	45@100MHz	750	0.77	620	K、J、G	Brown	Gray	Brown
1008C R20	200@25MHz	50@100MHz	750	0.81	500	K、J、G	Red	Black	Brown
1008C R22	220@25MHz	45@100MHz	700	0.84	500	K、J、G	Red	Red	Brown
1008C R24	240@25MHz	50@100MHz	600	0.84	500	K、J、G	Red	Yellow	Brown
1008C R27	270@25MHz	45@100MHz	600	0.91	500	K、J、G	Red	Violet	Brown
1008C R30	300@150MHz	40@100MHz	500	1.05	660	K、J、G	Orange	Black	Brown
1008C R33	330@25MHz	45@100MHz	570	1.05	450	K、J、G	Orange	Orange	Brown
1008C R36	360@150MHz	40@100MHz	500	1.05	660	K、J、G	Orange	Blue	Brown
1008C R39	390@25MHz	45@100MHz	500	1.12	470	K、J、G	Orange	White	Brown
1008C R43	430@150MHz	40@100MHz	425	1.19	600	K、J、G	Yellow	Orange	Brown
1008C R47	470@25MHz	45@100MHz	450	1.19	470	K、J、G	Yellow	Violet	Brown
1008C R56	560@25MHz	45@100MHz	415	1.33	400	K、J、G	Green	Blue	Brown
1008C R62	620@25MHz	45@100MHz	375	1.40	300	K、J、G	Blue	Red	Brown
1008C R68	680@25MHz	45@100MHz	375	1.47	400	K、J、G	Blue	Gray	Brown
1008C R75	750@25MHz	45@100MHz	360	1.54	360	K、J、G	Violet	Green	Brown
1008C R82	820@25MHz	45@100MHz	350	1.61	400	K、J、G	Gray	Red	Brown
1008C R91	910@25MHz	35@50MHz	320	1.68	380	K、J、G	White	Brown	Brown
1008C 1R0	1000@25MHz	35@50MHz	290	1.75	370	K、J、G	Brown	Black	Red
1008C 1R2	1200@7.9MHz	35@50MHz	250	2.00	310	K、J、G	Brown	Red	Red
1008C 1R5	1500@7.9MHz	28@50MHz	200	2.30	330	K、J、G	Brown	Green	Red
1008C 1R8	1800@7.9MHz	28@50MHz	160	2.60	300	K、J、G	Brown	Gray	Red
1008C 2R0	2000@7.9MHz	25@50MHz	160	2.80	280	K、J、G	Red	Black	Red
1008C 2R2	2200@7.9MHz	28@50MHz	160	2.80	280	K、J、G	Red	Red	Red
1008C 2R7	2700@7.9MHz	22@25MHz	140	3.20	290	K、J、G	Red	Violet	Red
1008C 3R3	3300@7.9MHz	22@25MHz	110	3.40	290	K、J、G	Orange	Orange	Red
1008C 3R9	3900@7.9MHz	20@25MHz	100	3.60	260	K、J、G	Orange	White	Red
1008C 4R7	4700@7.9MHz	20@25MHz	90	4.00	260	K、J、G	Yellow	Violet	Red

1、 Test equipment :
L/Q : HP4287A
SRF : HP4291B,HP8753E

2、 IDC : For 15℃ Temperature rise from 25℃ ambient.

3、 Operating temperature : -40℃~+125℃.

Packaging		DOC.NO	1008CG-type
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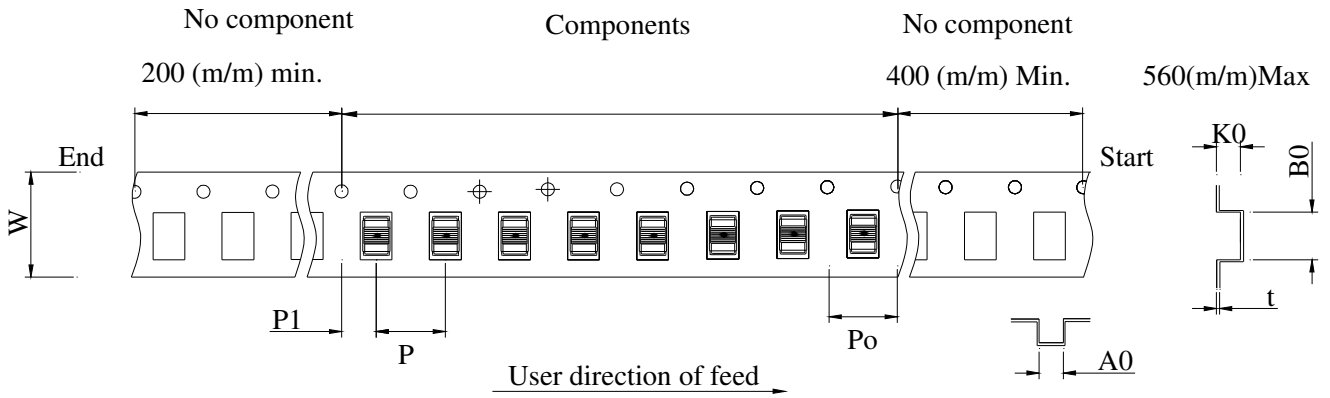
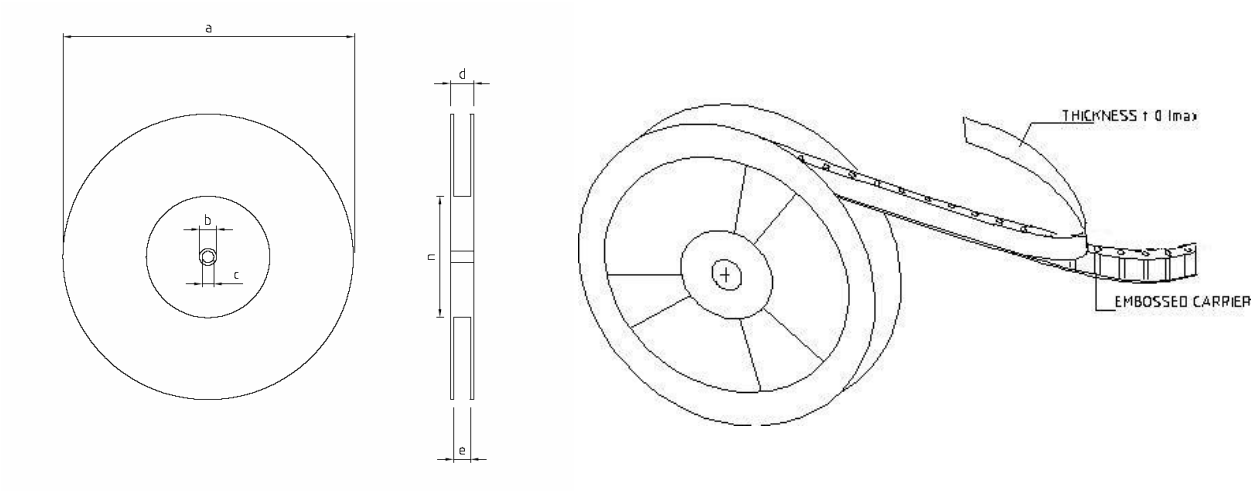




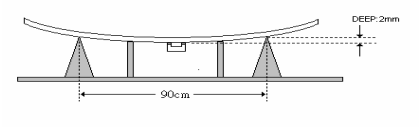
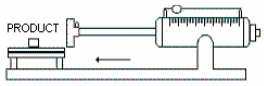
Product Series	t	PI	P	P_0	W	A_0	B_0	K_0	a	b	c	d	e	n
1008	0.25 ±0.05	2.0 ±0.05	4.0 ±0.1	4.0 ±0.1	8.0 ±0.2	2.73 ±0.1	2.90 ±0.1	2.34 ±0.1	178.0 ±2.0	21.0 ±0.8	13.0 ±0.8	12.5 MAX	8.4 ±1.0	50 MIN

Reel		5Reel / Box		6Box / Carton	
Q'ty(Pcs)	Size m/m	Q'ty(Pcs)	Size m/m	Q'ty(Pcs)	Size m/m
2,000	180 ϕ	10,000	182×182×80	60,000	540×210×205

1. Environmental Performance

NO	ITEM	SPECIFICATION	TEST CONDITION	TSET METHOD
1-1	TEMPERATURE CYCLE	APPEARANCE:NO DAMAGE L CHANGE:WITHIN±3% Q CHANGE:WITHIN±3%	ONE CYCLE STEP / TEMPERATURE(℃) / TIME(MIN) 1 / +125℃±5 / 30 2 / -65℃±5 / 30 TOTAL:10CYCLES	TO WRITE DOWN MEASURED RESULT FOR THE PARTS AFTER TEST AT ROOM TEMPERATURE FOR 1HOUR AND BEFRON TEST
1-2	HUMIDITY RESISTANCE		TEMPERATURE:40±2℃ RELATIVE HUMIDITY:90±5% TIME:96HRS	TO WRITE DOWN MEASURED RESULT FOR THE PARTS AFTER TEST AT ROOM TEMPERATURE FOR 1HOUR AND BEFRON TEST
1-3	LIFE TEST		TEMPERATURE:+75℃±5℃ TIME:300HRS	TO WRITE DOWN MEASURED RESULT FOR THE PARTS AFTER TEST AT ROOM TEMPERATURE FOR 1HOUR AND BEFRON TEST
1-4	LOWTEMPERATURE STORAGE		TEMPERATURE:-40℃±2℃ TIME:48±2HRS	TO WRITE DOWN MEASURED RESULT FOR THE PARTS AFTER TEST AT ROOM TEMPERATURE FOR 1HOUR AND BEFRON TEST
1-5	HIGHTEMPERATURE STORAGE		TEMPERATURE:+125℃±2℃ TIME: 48±2HRS	TO WRITE DOWN MEASURED RESULT FOR THE PARTS AFTER TEST AT ROOM TEMPERATURE FOR 1HOUR AND BEFRON TEST

2. Mechanical Performance

NO	ITEM	SPECIFICATION	TEST CONDITION
2-1	VIBRATION		TEST DEVICE SHALL BE SOLDERED ON THE SUBSTRATE OSCILLATION FREQUENCY:10TO 55TO10Hz FOR 1MIN AMPLITUDE:0.75mm TIME:2HRS:FOREACH AXIS(X,Y&Z), TOTAL 6HRS
2-2	RESISTANCE TO SOLDERING HEAT		SOLDER COMPOSITION: Sn/Ag/Cu=96.5/3.0/0.5 SOLDER TEMPERATURE:260±5℃ IMMERSION TIME:10±1SEC TOTAL:2 CYCLES
2-3	SOLDERABILITY	THE ELECTRODES SHALL BE AT LEAST 95% COVERED WITH NEW SOLDER COATIN	SOLDER COMPOSITION:Sn/Ag/Cu=96.5/3.0/0.5 SOLDER TEMPERATURE:230±5℃ IMMERSION TIME:5±0.5SEC
2-4	FLEXURE STRENGTH	THE BEING TRIED ARTICLE CAN'T CRACK OR SHED OFF OF SITUATION.	AFTER SOLDERING A CHIP TO A TEST SUBSTRATE,BEND THE USING THE FERROMOLYBDENUM MASS TO GET DOWN THE PCB BOARD TO PRESS TO BEND THE 2 mm DEPTH AND RETURN TO AGAIN THE BREAKOUT MAINTAINING THE 10SEC. SOLDERING SHALL BE RECOMMENDED PC BOARD PATTERN AND REFLOW SOLDERING. 
2-5	TERMINAL STRENGHTH	PRODUCT OF THE SERIES IS MORE THAN 4POUND	AFTER SOLDERING A CHIP TO A TEST SUBSTRATE,WITH THE 0.13~0.15mm THICK SOLDER. SOLDERING SHALL BE RECOMMENDED PC BOARD PATTERN AND REFLOW SOLDERING. THE THRUST ABOUT PUSHER PRODUCT WITH THE VELOCITY OF THE 20mms/1sec AFTER ACCOUNTING TO RETURN THE NULL. 

3. Recommended Lead-Free IR Reflow Conditions：